

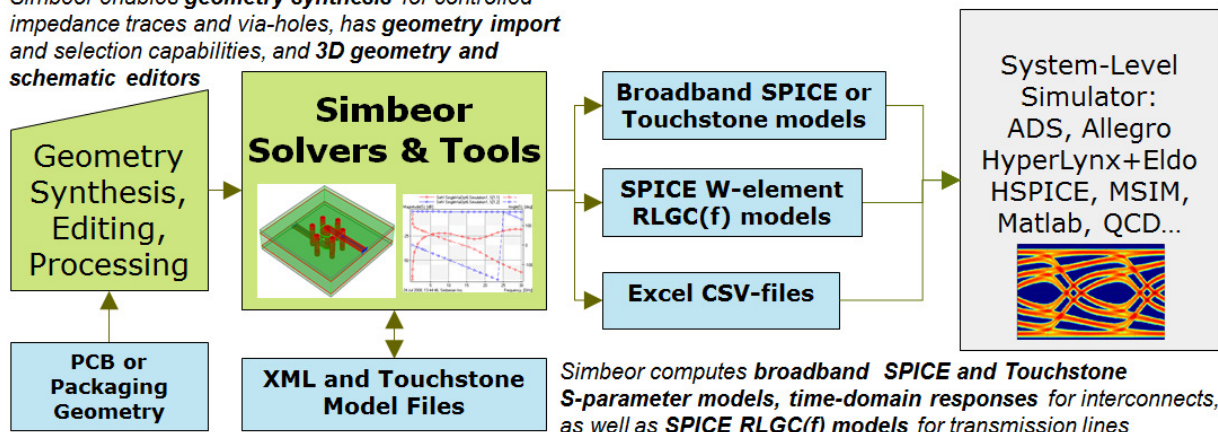
Simbeor®

Electromagnetic Signal Integrity Software™

Fast, Easy and Affordable Electromagnetic Software for Physical Design of PCB and Packaging Interconnects Operating at 6-100 Gb/s and Beyond

Faster data rates drive the need for design of minimal-reflection and low-loss interconnect links. **Simbeor is the one-stop solution for all interconnect budget exploration, design verification and macro-modeling tasks.** Simbeor is an industry-first measurement-validated tool to synthesize controlled-impedance geometry for transmission lines and via-holes, to build advanced electromagnetic models for all elements of PCB and packaging interconnects and to simulate a complete data link in frequency and time domains. The accuracy of the models is ensured in Simbeor through the use of advanced algorithms for 3D full wave analysis, benchmarking and experimental validation. **Simbeor beats the competition hands down, when it comes to validation of analysis with the measurements!** Simulation of data links with the electromagnetic models eliminates uncertainties of simplified models and guaranties the first pass design success.

*Simbeor enables **geometry synthesis** for controlled impedance traces and via-holes, has **geometry import and selection capabilities**, and **3D geometry and schematic editors***



Use Simbeor For...

- PCB and packaging interconnects budget exploration and design verification with advanced 3D full-wave de-compositional frequency and time-domain compliance analyses
- Synthesis of geometry for impedance controlled transmission lines and minimal-reflection via-holes
- Advanced electromagnetic modeling of transmission lines, via-holes and discontinuities in data links
- Building rational compact and broadband SPICE macro-models for consistent time and frequency domain analyses of interconnects, connectors, packages, and complete data links
- Automation of S-parameter models quality assurance and all macro-modeling tasks
- Identification of models for conductive and dielectric materials with measurements (patent pending)
- Clarifying doubts about results obtained with measurements or with your current EM or SI tool

Simbeor Technology

Simbeor innovative technology combines results of over 25 years of research and development. Hybrid simulation technique is based on the method of lines (MoL) and Trefftz finite element method (TFEM). MoL provides fast and accurate solution for multi-layered dielectrics and metal planes. TFEM is used to simulate trace conductors interior with rough surfaces. Method of simultaneous diagonalization is used for extraction of parameters of multi-conductor transmission lines and periodic structures and for precise de-embedding of discontinuities. Fast and accurate de-compositional analysis with rational macro-modeling is used to simulate a complete communication link consistently in frequency and time domains.

Simbeor®

Benefits	Features
Ease of use	Wizards to enter 3D geometry of transmission lines and via-holes with all elements for EM analysis Wizards to create different types of circuits and simulations and to output final models Import of PCB geometry files with geometry selection and automatic de-composition capabilities Intuitive network and geometry editors with synchronized graphical and tree views Automatic RLGC(f) p.u.l. parameters extraction for t-lines and periodic structures with output in SPICE format Automatic de-embedded multiport S-parameters extraction with output in Touchstone and SPICE formats Interactive 2D graphs to plot parameters of t-lines, and S, Y and Z parameters and time-domain responses
Efficiency	Fast 64-bit parallelized electromagnetic analysis and rational macro-modeling engines Fast and accurate de-compositional frequency, TDR/TDR and PRBS compliance analyses of interconnects Fast synthesis of geometry for single and differential controlled-impedance traces and via-holes Integrated synthesis of broadband SPICE macro-models for components and for complete data channel Automation of S-parameters quality assurance and all macro-modeling tasks with Touchstone Analyzer™ tool Automatic processing of geometric symmetry (5 types) to accelerate EM analysis and preserve accuracy Fast interactive tuning and optimization with SiTune™ tool Parameterized solution spaces to quickly find optimal geometry
Accuracy	Validated with benchmarks and measurements from DC to 50 GHz Accurate broadband material parameters identification with unique patent-pending algorithm Causal multi-pole and wideband Debye dielectric dispersion and loss models with loss tangent restoration Simulation of regular and multilayered conductors with unique models for nickel and surface roughness Precise fitting with passive and causal rational compact models with extrapolation to DC and to infinity Precise de-embedding of discontinuities and transitions in multi-conductor lines Consistent frequency and time-domain analyses with S-parameter models
Affordability	Low cost, flexible subscription scheme, node-locked and floating or network licenses

System Requirements

- Windows XP/Vista/7 (32-bit and 64-bit) and compatible operating systems
- 1 GHz or faster processor with 1 GB memory, 2-3 GHz systems with 2 GB memory (4-8 GB for 64-bit version) are preferable
- 3D graphic card with OpenGL support

Support, Prices and Ordering

Distributed By

Singapore:

Polar Instruments (Asia Pacific) Pte Ltd: T +65 6873 7470, mail@polarinstruments.asia

East China (Shanghai):

Polar Instruments (China) Ltd: T +86 21 3530 7470, china@polarinstruments.asia

South China (Zhuhai):

Polar Instruments (China) Ltd: T +86 756 336 7470, china@polarinstruments.asia

Japan:

Polar Instruments (Japan) K.K.: T +81 44 276 9112, japan@polarinstruments.asia

Rest of Asia:

Polar Instruments (Asia Pacific) Pte Ltd: T +65 6873 7470, mail@polarinstruments.asia

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